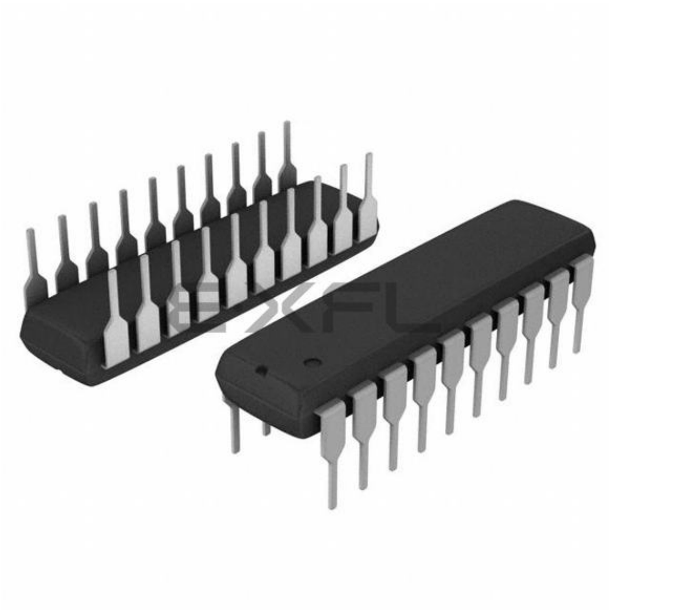


What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	20-DIP (0.300", 7.62mm)
Supplier Device Package	20-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1829-i-p

3.4 Stack

All devices have a 16-level x 15-bit wide hardware stack (refer to Figures 3-4 through 3-7). The stack space is not part of either program or data space. The PC is PUSHed onto the stack when `CALL` or `CALLW` instructions are executed or an interrupt causes a branch. The stack is POPed in the event of a `RETURN`, `RETLW` or a `RETFIE` instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer if the STVREN bit is programmed to '0' (Configuration Word 2). This means that after the stack has been PUSHed sixteen times, the seventeenth PUSH overwrites the value that was stored from the first PUSH. The eighteenth PUSH overwrites the second PUSH (and so on). The STKOVF and STKUNF flag bits will be set on an Overflow/Underflow, regardless of whether the Reset is enabled.

Note 1:	There are no instructions/mnemonics called PUSH or POP. These are actions that occur from the execution of the `CALL`, `CALLW`, `RETURN`, `RETLW` and `RETFIE` instructions or the vectoring to an interrupt address.

3.4.1 ACCESSING THE STACK

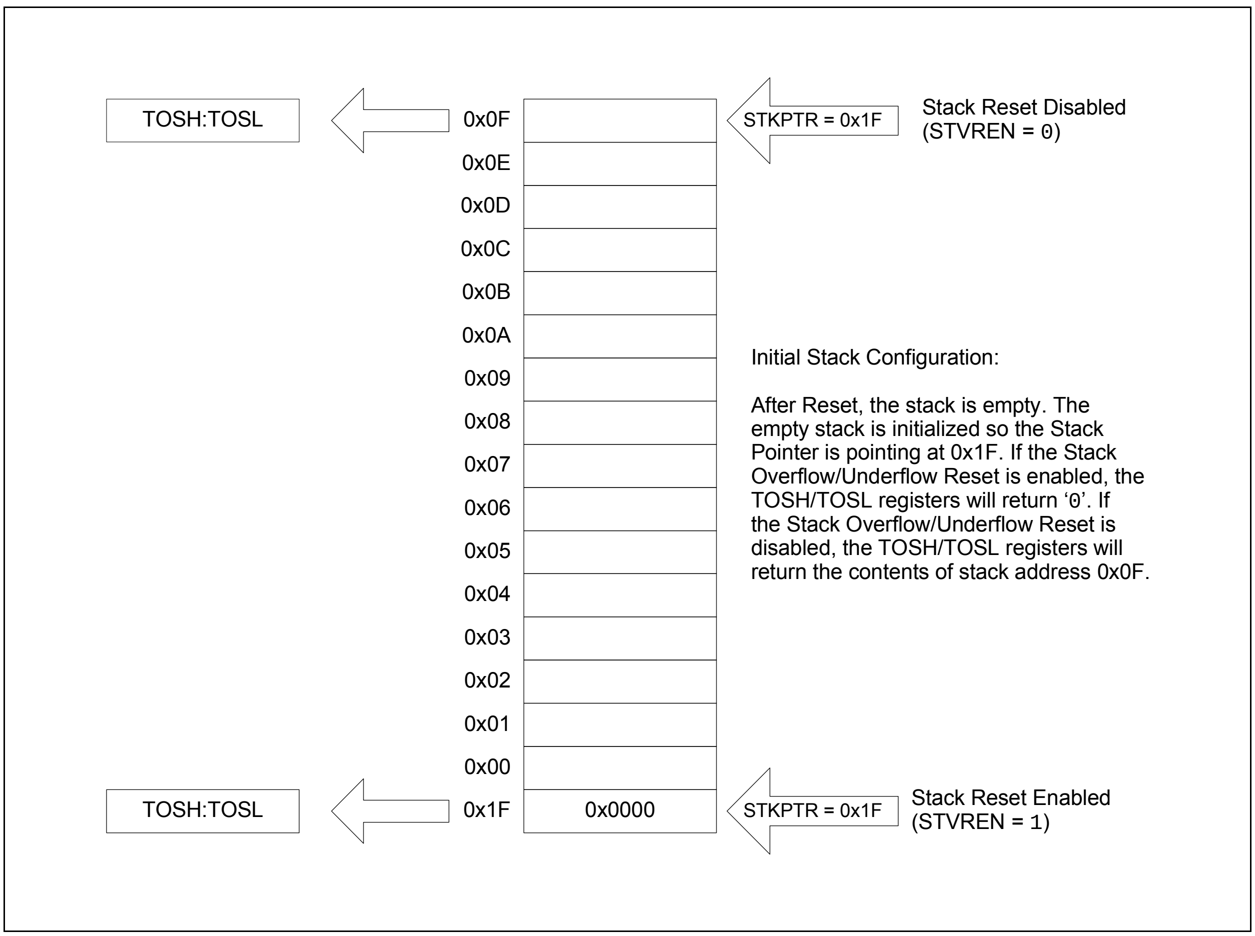
The stack is available through the TOSH, TOSL and STKPTR registers. STKPTR is the current value of the Stack Pointer. TOSH:TOSL register pair points to the TOP of the stack. Both registers are read/writable. TOS is split into TOSH and TOSL due to the 15-bit size of the PC. To access the stack, adjust the value of STKPTR, which will position TOSH:TOSL, then read/write to TOSH:TOSL. STKPTR is five bits to allow detection of overflow and underflow.

Note:	Care should be taken when modifying the STKPTR while interrupts are enabled.

During normal program operation, `CALL`, `CALLW` and Interrupts will increment STKPTR while `RETLW`, `RETURN`, and `RETFIE` will decrement STKPTR. At any time STKPTR can be inspected to see how much stack is left. The STKPTR always points at the currently used place on the stack. Therefore, a `CALL` or `CALLW` will increment the STKPTR and then write the PC, and a return will unload the PC and then decrement the STKPTR.

Reference Figure 3-4 through Figure 3-7 for examples of accessing the stack.

FIGURE 3-4: ACCESSING THE STACK EXAMPLE 1



5.4 Two-Speed Clock Start-up Mode

Two-Speed Start-up mode provides additional power savings by minimizing the latency between external oscillator start-up and code execution. In applications that make heavy use of the Sleep mode, Two-Speed Start-up will remove the external oscillator start-up time from the time spent awake and can reduce the overall power consumption of the device. This mode allows the application to wake-up from Sleep, perform a few instructions using the INTOSC internal oscillator block as the clock source and go back to Sleep without waiting for the external oscillator to become stable.

Two-Speed Start-up provides benefits when the oscillator module is configured for LP, XT or HS modes. The Oscillator Start-up Timer (OST) is enabled for these modes and must count 1024 oscillations before the oscillator can be used as the system clock source.

If the oscillator module is configured for any mode other than LP, XT or HS mode, then Two-Speed Start-up is disabled. This is because the external clock oscillator does not require any stabilization time after POR or an exit from Sleep.

If the OST count reaches 1024 before the device enters Sleep mode, the OSTS bit of the OSCSTAT register is set and program execution switches to the external oscillator. However, the system may never operate from the external oscillator if the time spent awake is very short.

Note:	Executing a `SLEEP` instruction will abort the oscillator start-up time and will cause the OSTS bit of the OSCSTAT register to remain clear.

5.4.1 TWO-SPEED START-UP MODE CONFIGURATION

Two-Speed Start-up mode is configured by the following settings:

- IESO (of the Configuration Word 1) = `1`; Internal/External Switchover bit (Two-Speed Start-up mode enabled).
- SCS (of the OSCCON register) = `00`.
- FOSC<2:0> bits in the Configuration Word 1 configured for LP, XT or HS mode.

Two-Speed Start-up mode is entered after:

- Power-on Reset (POR) and, if enabled, after Power-up Timer (PWRT) has expired, or
- Wake-up from Sleep.

Note:	When FSCM is enabled, Two-Speed Start-up will automatically be enabled.

TABLE 5-1: OSCILLATOR SWITCHING DELAYS

Switch From	Switch To	Frequency	Oscillator Delay
Sleep/POR	LFINTOSC(1) MFINTOSC(1) HFINTOSC(1)	31 kHz 31.25 kHz-500 kHz 31.25 kHz-16 MHz	Oscillator Warm-up Delay (T_{WARM})
Sleep/POR	EC, RC(1)	DC – 32 MHz	2 cycles
LFINTOSC	EC, RC(1)	DC – 32 MHz	1 cycle of each
Sleep/POR	Timer1 Oscillator LP, XT, HS(1)	32 kHz-20 MHz	1024 Clock Cycles (OST)
Any clock source	MFINTOSC(1) HFINTOSC(1)	31.25 kHz-500 kHz 31.25 kHz-16 MHz	2 μs (approx.)
Any clock source	LFINTOSC(1)	31 kHz	1 cycle of each
Any clock source	Timer1 Oscillator	32 kHz	1024 Clock Cycles (OST)
PLL inactive	PLL active	16-32 MHz	2 ms (approx.)

Note 1: PLL inactive.

REGISTER 5-3: OSCTUNE: OSCILLATOR TUNING REGISTER

U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	TUN<5:0>					
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **TUN<5:0>:** Frequency Tuning bits
`011111` = Maximum frequency
`011110` =
•
•
•
`000001` =
`000000` = Oscillator module is running at the factory-calibrated frequency.
`111111` =
•
•
•
`100000` = Minimum frequency

TABLE 5-2: SUMMARY OF REGISTERS ASSOCIATED WITH CLOCK SOURCES

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
OSCCON	SPLLEN	IRCF<3:0>				—	SCS<1:0>		68
OSCSTAT	T1OSCR	PLLR	OSTS	HFIOFR	HFIOFL	MFIOFR	LFIOFR	HFIOFS	69
OSCTUNE	—	—	TUN<5:0>						70
PIE2	OSFIE	C2IE	C1IE	EEIE	BCL1IE	—	—	CCP2IE	89
PIR2	OSFIF	C2IF	C1IF	EEIF	BCL1IF	—	—	CCP2IF	93
T1CON	TMR1CS<1:0>		T1CKPS<1:0>		T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	185

Legend: — Unimplemented location, read as ‘0’. Shaded cells are not used by clock sources.

TABLE 5-3: SUMMARY OF CONFIGURATION WORD WITH CLOCK SOURCES

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	FCMEN	IESO	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		$\overline{\text{CPD}}$	48
	7:0	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>			

Legend: — Unimplemented location, read as ‘0’. Shaded cells are not used by clock sources.

8.6.6 PIR1 REGISTER

The PIR1 register contains the interrupt flag bits, as shown in Register 8-6.

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 8-6: PIR1: PERIPHERAL INTERRUPT REQUEST REGISTER 1

R/W-0/0	R/W-0/0	R-0/0	R-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7 **TMR1GIF:** Timer1 Gate Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 6 **ADIF:** A/D Converter Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 5 **RCIF:** USART Receive Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 4 **TXIF:** USART Transmit Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 3 **SSP1IF:** Synchronous Serial Port (MSSP) Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 2 **CCP1IF:** CCP1 Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 1 **TMR2IF:** Timer2 to PR2 Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

bit 0 **TMR1IF:** Timer1 Overflow Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending

11.3.2 ERASING FLASH PROGRAM MEMORY

While executing code, program memory can only be erased by rows. To erase a row:

1. Load the EEADRH:EEADRL register pair with the address of new row to be erased.
2. Clear the CFGS bit of the EECON1 register.
3. Set the EEPGD, FREE, and WREN bits of the EECON1 register.
4. Write 55h, then AAh, to EECON2 (Flash programming unlock sequence).
5. Set control bit WR of the EECON1 register to begin the erase operation.
6. Poll the FREE bit in the EECON1 register to determine when the row erase has completed.

See Example 11-4.

After the "`BSF EECON1,WR`" instruction, the processor requires two cycles to set up the erase operation. The user must place two `NOP` instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms erase time. This is not Sleep mode as the clocks and peripherals will continue to run. After the erase cycle, the processor will resume operation with the third instruction after the EECON1 write instruction.

11.3.3 WRITING TO FLASH PROGRAM MEMORY

Program memory is programmed using the following steps:

1. Load the starting address of the word(s) to be programmed.
2. Load the write latches with data.
3. Initiate a programming operation.
4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 11-2 for more details. The write latches are aligned to the address boundary defined by EEADRL as shown in Table 11-1. Write operations do not cross these boundaries. At the completion of a program memory write operation, the write latches are reset to contain 0x3FFF.

The following steps should be completed to load the write latches and program a block of program memory. These steps are divided into two parts. First, all write latches are loaded with data except for the last program memory location. Then, the last write latch is loaded and the programming sequence is initiated. A special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. This unlock sequence should not be interrupted.

1. Set the EEPGD and WREN bits of the EECON1 register.
2. Clear the CFGS bit of the EECON1 register.
3. Set the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '`1`', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
4. Load the EEADRH:EEADRL register pair with the address of the location to be written.
5. Load the EEDATH:EEDATL register pair with the program memory data to be written.
6. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The write latch is now loaded.
7. Increment the EEADRH:EEADRL register pair to point to the next location.
8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
9. Clear the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '`0`', the write sequence will initiate the write to Flash program memory.
10. Load the EEDATH:EEDATL register pair with the program memory data to be written.
11. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The entire latch block is now written to Flash program memory.

It is not necessary to load the entire write latch block with user program data. However, the entire write latch block will be written to program memory.

An example of the complete write sequence for eight words is shown in Example 11-5. The initial address is loaded into the EEADRH:EEADRL register pair; the eight words of data are loaded using indirect addressing.

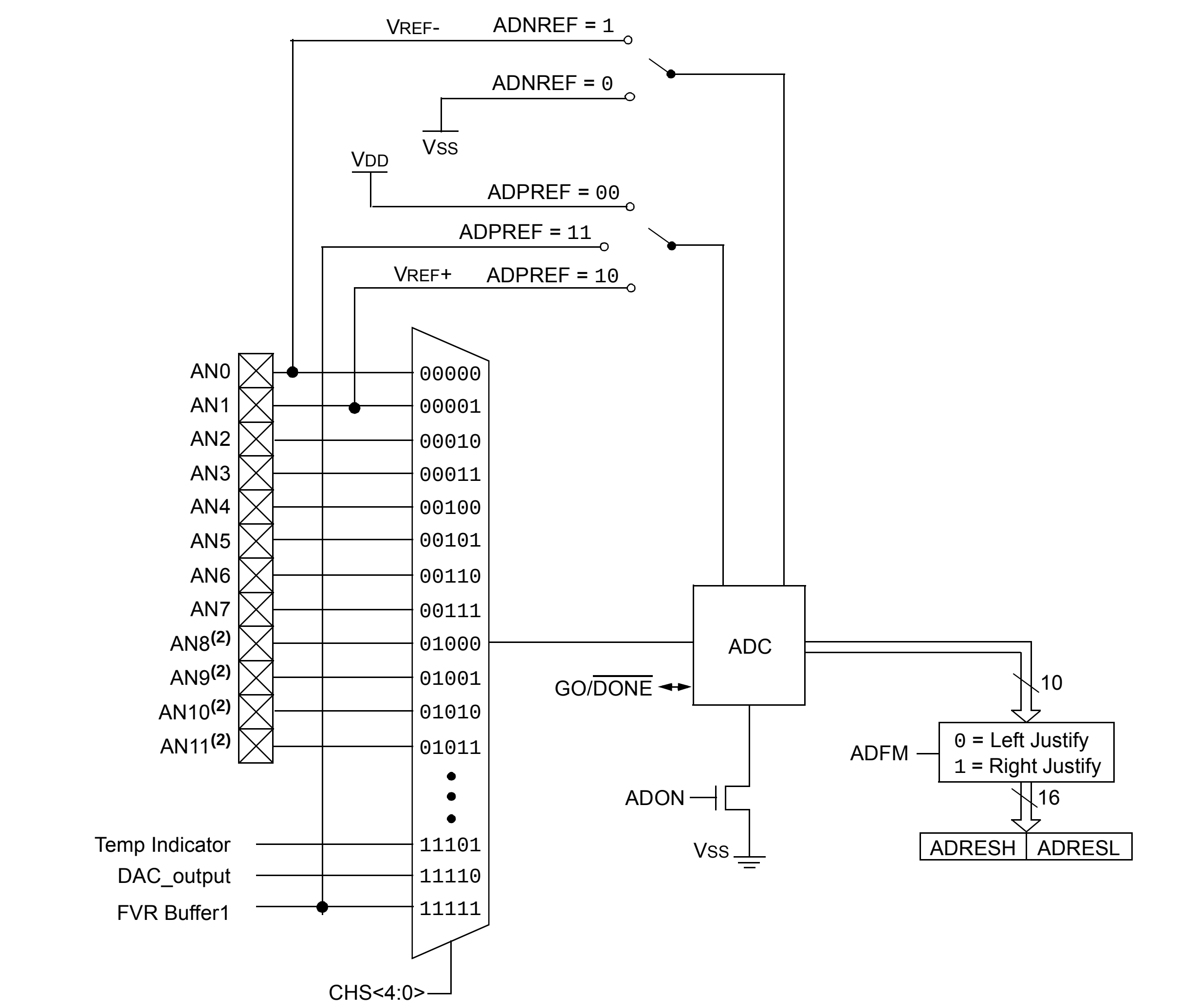
16.0 ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

The Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 10-bit binary representation of that signal. This device uses analog inputs, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a 10-bit binary result via successive approximation and stores the conversion result into the ADC result registers (ADRESH:ADRESL register pair). Figure 16-1 shows the block diagram of the ADC.

The ADC voltage reference is software selectable to be either internally generated or externally supplied.

The ADC can generate an interrupt upon completion of a conversion. This interrupt can be used to wake-up the device from Sleep.

FIGURE 16-1: ADC BLOCK DIAGRAM



Note 1: When ADON = 0, all multiplexer inputs are disconnected.

2: PIC16(L)F1829 only.

16.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

16.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 12.0 “I/O Ports”** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

16.1.2 CHANNEL SELECTION

There are up to 15 channel selections available:

- AN<7:0> pins (PIC16(L)F1825 only)
- AN<11:0> pins (PIC16(L)F1829 only)
- Temperature Indicator
- DAC_output
- FVR Buffer1

Refer to **Section 17.0 “Digital-to-Analog Converter (DAC) Module”**, **Section 14.0 “Fixed Voltage Reference (FVR)”** and **Section 15.0 “Temperature Indicator Module”** for more information on these channel selections.

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 16.2 “ADC Operation”** for more information.

16.1.3 ADC VOLTAGE REFERENCE

The ADPREF bits of the ADCON1 register provides control of the positive voltage reference. The positive voltage reference can be:

- VREF+ pin
- VDD
- FVR 2.048V
- FVR 4.096V (Not available on LF devices)

The ADNREF bits of the ADCON1 register provides control of the negative voltage reference. The negative voltage reference can be:

- VREF- pin
- VSS

See **Section 14.0 “Fixed Voltage Reference (FVR)”** for more details on the Fixed Voltage Reference.

16.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

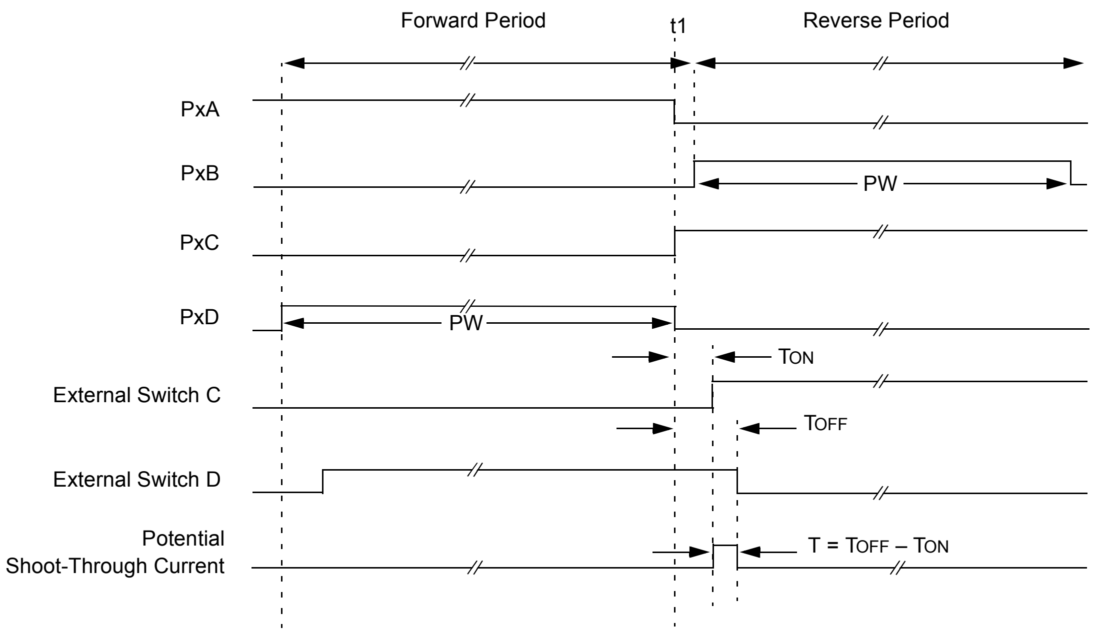
- FOSC/2
- FOSC/4
- FOSC/8
- FOSC/16
- FOSC/32
- FOSC/64
- FRC (dedicated internal oscillator)

The time to complete one bit conversion is defined as TAD. One full 10-bit conversion requires 11.5 TAD periods as shown in Figure 16-2.

For correct conversion, the appropriate TAD specification must be met. Refer to the A/D conversion requirements in **Section 30.0 “Electrical Specifications”** for more information. Table 16-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

FIGURE 24-13: EXAMPLE OF PWM DIRECTION CHANGE AT NEAR 100% DUTY CYCLE



Note 1: All signals are shown as active-high.

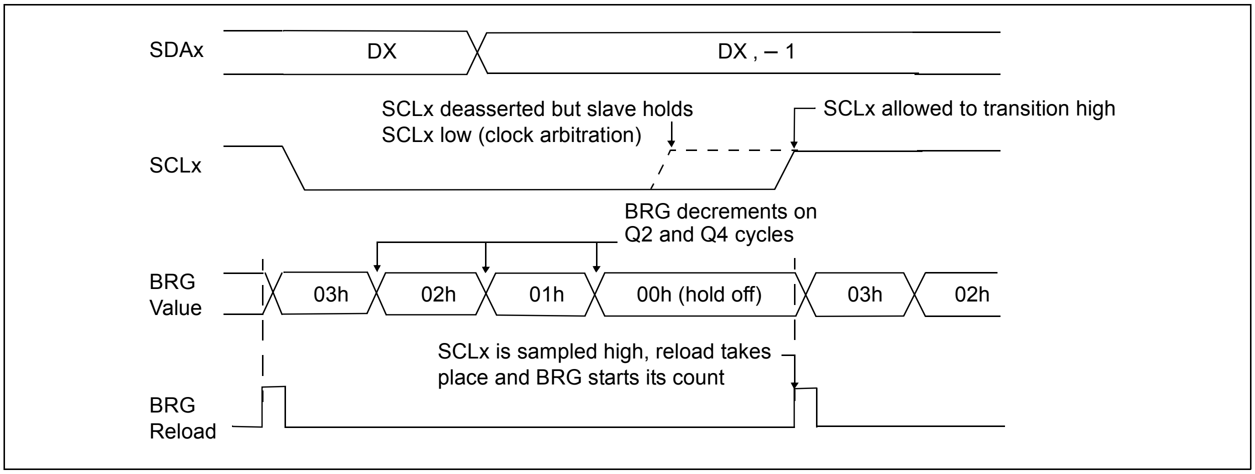
2: TON is the turn-on delay of power switch QC and its driver.

3: TOFF is the turn-off delay of power switch QD and its driver.

25.6.2 CLOCK ARBITRATION

Clock arbitration occurs when the master, during any receive, transmit or Repeated Start/Stop condition, releases the SCLx pin (SCLx allowed to float high). When the SCLx pin is allowed to float high, the Baud Rate Generator (BRG) is suspended from counting until the SCLx pin is actually sampled high. When the SCLx pin is sampled high, the Baud Rate Generator is reloaded with the contents of SSPxADD<7:0> and begins counting. This ensures that the SCLx high time will always be at least one BRG rollover count in the event that the clock is held low by an external device (Figure 25-25).

FIGURE 25-25: BAUD RATE GENERATOR TIMING WITH CLOCK ARBITRATION



25.6.3 WCOL STATUS FLAG

If the user writes the SSPxBUF when a Start, Restart, Stop, Receive or Transmit sequence is in progress, the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur). Any time the WCOL bit is set it indicates that an action on SSPxBUF was attempted while the module was not Idle.

Note:	Because queuing of events is not allowed, writing to the lower five bits of SSPxCON2 is disabled until the Start condition is complete.

25.6.6 I^{2}C MASTER MODE TRANSMISSION

Transmission of a data byte, a 7-bit address or the other half of a 10-bit address is accomplished by simply writing a value to the SSPxBUF register. This action will set the Buffer Full flag bit, BF and allow the Baud Rate Generator to begin counting and start the next transmission. Each bit of address/data will be shifted out onto the SDAx pin after the falling edge of SCLx is asserted. SCLx is held low for one Baud Rate Generator rollover count (TBRG). Data should be valid before SCLx is released high. When the SCLx pin is released high, it is held that way for TBRG. The data on the SDAx pin must remain stable for that duration and some hold time after the next falling edge of SCLx. After the eighth bit is shifted out (the falling edge of the eighth clock), the BF flag is cleared and the master releases SDAx. This allows the slave device being addressed to respond with an $\overline{ACK}$ bit during the ninth bit time if an address match occurred, or if data was received properly. The status of $\overline{ACK}$ is written into the ACKSTAT bit on the rising edge of the ninth clock. If the master receives an Acknowledge, the Acknowledge Status bit, ACKSTAT, is cleared. If not, the bit is set. After the ninth clock, the SSPxIF bit is set and the master clock (Baud Rate Generator) is suspended until the next data byte is loaded into the SSPxBUF, leaving SCLx low and SDAx unchanged (Figure 25-28).

After the write to the SSPxBUF, each bit of the address will be shifted out on the falling edge of SCLx until all seven address bits and the R/$\overline{W}$ bit are completed. On the falling edge of the eighth clock, the master will release the SDAx pin, allowing the slave to respond with an Acknowledge. On the falling edge of the ninth clock, the master will sample the SDAx pin to see if the address was recognized by a slave. The status of the $\overline{ACK}$ bit is loaded into the ACKSTAT Status bit of the SSPxCON2 register. Following the falling edge of the ninth clock transmission of the address, the SSPxIF is set, the BF flag is cleared and the Baud Rate Generator is turned off until another write to the SSPxBUF takes place, holding SCLx low and allowing SDAx to float.

25.6.6.1 BF Status Flag

In Transmit mode, the BF bit of the SSPxSTAT register is set when the CPU writes to SSPxBUF and is cleared when all eight bits are shifted out.

25.6.6.2 WCOL Status Flag

If the user writes the SSPxBUF when a transmit is already in progress (i.e., SSPxSR is still shifting out a data byte), the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

WCOL must be cleared by software before the next transmission.

25.6.6.3 ACKSTAT Status Flag

In Transmit mode, the ACKSTAT bit of the SSPxCON2 register is cleared when the slave has sent an Acknowledge ($\overline{ACK}$ = 0) and is set when the slave does not Acknowledge ($\overline{ACK}$ = 1). A slave sends an Acknowledge when it has recognized its address (including a general call), or when the slave has properly received its data.

25.6.6.4 Typical Transmit Sequence:

1. The user generates a Start condition by setting the SEN bit of the SSPxCON2 register.
2. SSPxIF is set by hardware on completion of the Start.
3. SSPxIF is cleared by software.
4. The MSSPx module will wait the required start time before any other operation takes place.
5. The user loads the SSPxBUF with the slave address to transmit.
6. Address is shifted out the SDAx pin until all eight bits are transmitted. Transmission begins as soon as SSPxBUF is written to.
7. The MSSPx module shifts in the $\overline{ACK}$ bit from the slave device and writes its value into the ACKSTAT bit of the SSPxCON2 register.
8. The MSSPx module generates an interrupt at the end of the ninth clock cycle by setting the SSPxIF bit.
9. The user loads the SSPxBUF with eight bits of data.
10. Data is shifted out the SDAx pin until all eight bits are transmitted.
11. The MSSPx module shifts in the $\overline{ACK}$ bit from the slave device and writes its value into the ACKSTAT bit of the SSPxCON2 register.
12. Steps 8-11 are repeated for all transmitted data bytes.
13. The user generates a Stop or Restart condition by setting the PEN or RSEN bits of the SSPxCON2 register. Interrupt is generated once the Stop/Restart condition is complete.

25.6.13.2 Bus Collision During a Repeated Start Condition

During a Repeated Start condition, a bus collision occurs if:

a) A low level is sampled on SDAx when SCLx goes from low level to high level. (CASE 1)

b) SCLx goes low before SDAx is asserted low, indicating that another master is attempting to transmit a data '1'. (CASE 2)

When the user releases SDAx and the pin is allowed to float high, the BRG is loaded with SSPxADD and counts down to zero. The SCLx pin is then deasserted and when sampled high, the SDAx pin is sampled.

If SDAx is low, a bus collision has occurred (i.e., another master is attempting to transmit a data '0' (Figure 25-36). If SDAx is sampled high, the BRG is reloaded and begins counting. If SDAx goes from high-to-low before the BRG times out, no bus collision occurs because no two masters can assert SDAx at exactly the same time.

If SCLx goes from high-to-low before the BRG times out and SDAx has not already been asserted, a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition (Figure 25-37).

If, at the end of the BRG time-out, both SCLx and SDAx are still high, the SDAx pin is driven low and the BRG is reloaded and begins counting. At the end of the count, regardless of the status of the SCLx pin, the SCLx pin is driven low and the Repeated Start condition is complete.

FIGURE 25-36: BUS COLLISION DURING A REPEATED START CONDITION (CASE 1)

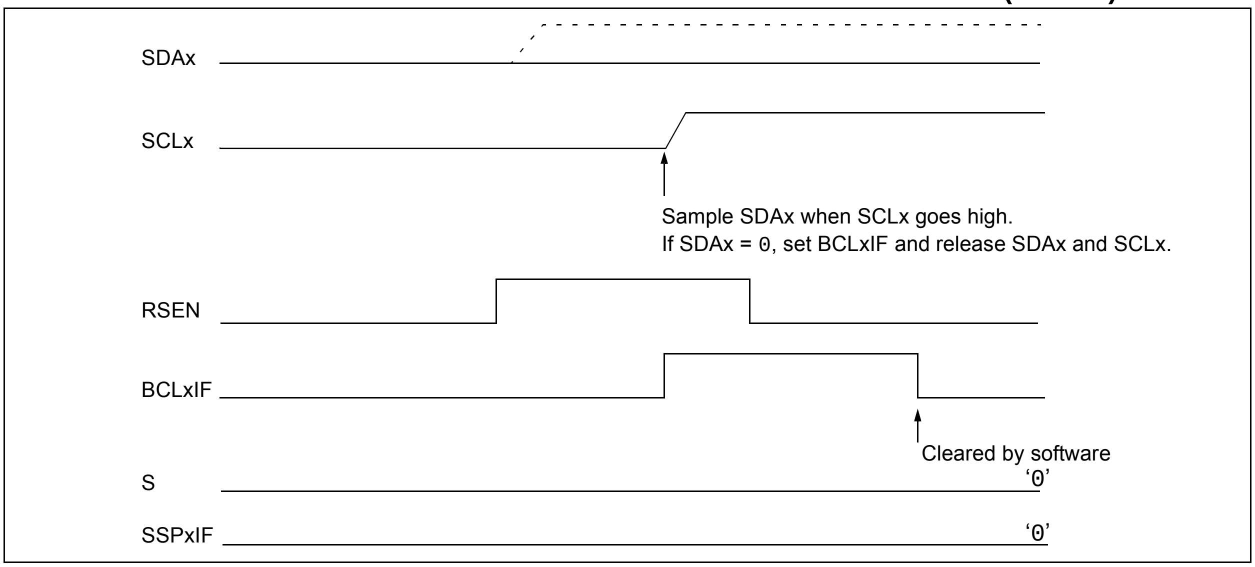
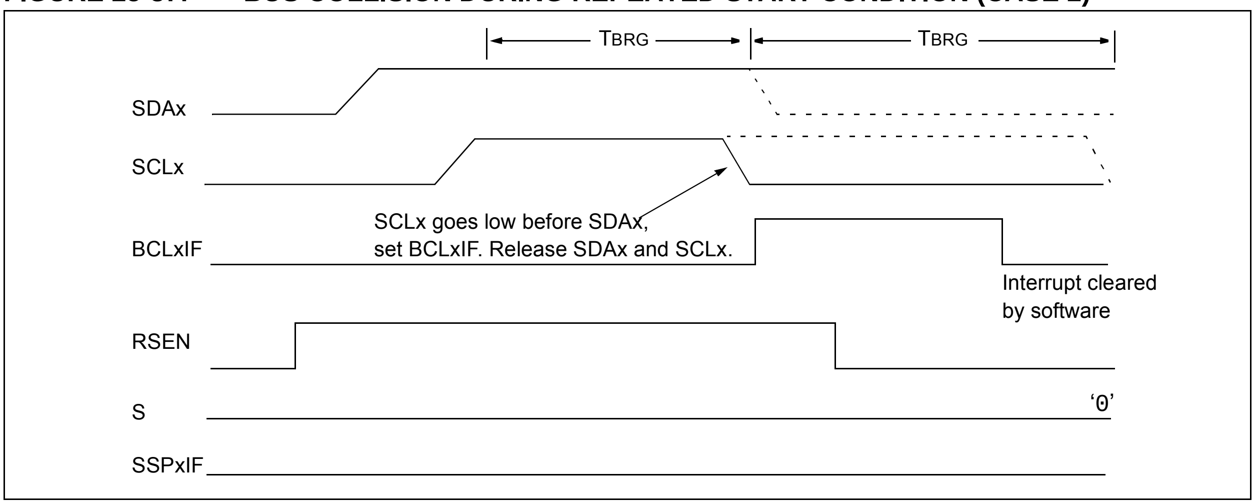


FIGURE 25-37: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)



26.2 Clock Accuracy with Asynchronous Operation

The factory calibrates the internal oscillator block output (INTOSC). However, the INTOSC frequency may drift as VDD or temperature changes, and this directly affects the asynchronous baud rate. Two methods may be used to adjust the baud rate clock, but both require a reference clock source of some kind.

The first (preferred) method uses the OSCTUNE register to adjust the INTOSC output. Adjusting the value in the OSCTUNE register allows for fine resolution changes to the system clock source. See **Section 5.2.2 "Internal Clock Sources"** for more information.

The other method adjusts the value in the Baud Rate Generator. This can be done automatically with the Auto-Baud Detect feature (see **Section 26.3.1 "Auto-Baud Detect"**). There may not be fine enough resolution when adjusting the Baud Rate Generator to compensate for a gradual change in the peripheral clock frequency.

REGISTER 26-1: TXSTA: TRANSMIT STATUS AND CONTROL REGISTER

R/W-/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R-1/1	R/W-0/0
CSRC	TX9	TXEN(1)	SYNC	SENDB	BRGH	TRMT	TX9D
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **CSRC:** Clock Source Select bit
Asynchronous mode:
Don't care
Synchronous mode:
1 = Master mode (clock generated internally from BRG)
0 = Slave mode (clock from external source)

bit 6 **TX9:** 9-bit Transmit Enable bit
1 = Selects 9-bit transmission
0 = Selects 8-bit transmission

bit 5 **TXEN:** Transmit Enable bit(1)
1 = Transmit enabled
0 = Transmit disabled

bit 4 **SYNC:** EUSART Mode Select bit
1 = Synchronous mode
0 = Asynchronous mode

bit 3 **SENDB:** Send Break Character bit
Asynchronous mode:
1 = Send Sync Break on next transmission (cleared by hardware upon completion)
0 = Sync Break transmission completed
Synchronous mode:
Don't care

bit 2 **BRGH:** High Baud Rate Select bit
Asynchronous mode:
1 = High speed
0 = Low speed
Synchronous mode:
Unused in this mode

bit 1 **TRMT:** Transmit Shift Register Status bit
1 = TSR empty
0 = TSR full

bit 0 **TX9D:** Ninth bit of Transmit Data
Can be address/data bit or a parity bit.

Note 1: SREN/CREN overrides TXEN in Sync mode.

MOVWI — Move W to INDFn

Syntax: [*label*] MOVWI ++FSRn
[*label*] MOVWI --FSRn
[*label*] MOVWI FSRn++
[*label*] MOVWI FSRn--
[*label*] MOVWI k[FSRn]

Operands: $n \in [0,1]$
$mm \in [00,01, 10, 11]$
$-32 \leq k \leq 31$

Operation: W → INDFn
Effective address is determined by
- FSR + 1 (preincrement)
- FSR - 1 (predecrement)
- FSR + k (relative offset)

After the Move, the FSR value will be either:
- FSR + 1 (all increments)
- FSR - 1 (all decrements)

Unchanged

Status Affected: None

Mode	Syntax	mm
Preincrement	++FSRn	00
Predecrement	--FSRn	01
Postincrement	FSRn++	10
Postdecrement	FSRn--	11

Description: This instruction is used to move data between W and one of the indirect registers (INDFn). Before/after this move, the pointer (FSRn) is updated by pre/post incrementing/decrementing it.

Note: The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the FSRn.

FSRn is limited to the range 0000h - FFFFh. Incrementing/decrementing it beyond these bounds will cause it to wrap-around.

The increment/decrement operation on FSRn WILL NOT affect any Status bits.

NOP — No Operation

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Description: No operation.

Words: 1

Cycles: 1

Example: `NOP`

OPTION — Load OPTION_REG Register with W

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION_REG

Status Affected: None

Description: Move data from W register to OPTION_REG register.

Words: 1

Cycles: 1

Example: `OPTION`

Before Instruction
OPTION_REG = 0xFF
W = 0x4F
After Instruction
OPTION_REG = 0x4F
W = 0x4F

RESET — Software Reset

Syntax: [*label*] RESET

Operands: None

Operation: Execute a device Reset. Resets the nRI flag of the PCON register.

Status Affected: None

Description: This instruction provides a way to execute a hardware Reset by software.

30.2 DC Characteristics: PIC16(L)F1825/9-I/E (Industrial, Extended) (Continued)

PIC16LF1825/9	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended
PIC16F1825/9	**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						VDD	Note
	Supply Current (IDD)(1, 2)						
D020		—	2.7	3.6	mA	3.0	FOSC = 32 MHz HS Oscillator mode **(Note 4)**
		—	3.2	4.2	mA	3.6	
D020		—	2.7	4.0	mA	3.0	FOSC = 32 MHz HS Oscillator mode **(Note 4)**
		—	3.2	4.3	mA	5.0	
D021		—	222	350	μA	1.8	FOSC = 4 MHz EXTRC mode **(Note 5)**
		—	400	690	μA	3.0	
D021		—	240	500	μA	1.8	FOSC = 4 MHz EXTRC mode **(Note 5)**
		—	416	800	μA	3.0	
		—	497	900	μA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{\text{MCLR}}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: 8 MHz internal RC oscillator with 4xPLL enabled.

4: 8 MHz crystal oscillator with 4xPLL enabled.

5: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ..

FIGURE 31-33: IPD, CAPACITIVE SENSING (CPS) MODULE, MEDIUM-CURRENT RANGE, CPSRM = 0, PIC16LF1825/9 ONLY

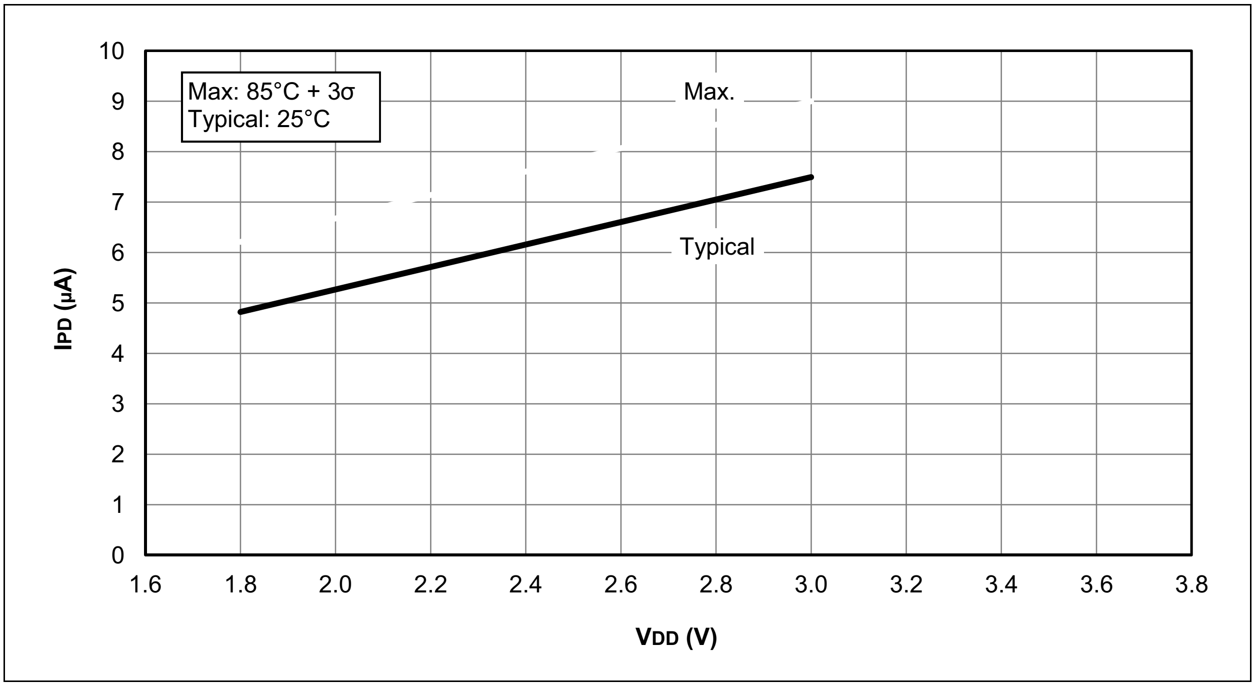


FIGURE 31-34: IPD, CAPACITIVE SENSING (CPS) MODULE, MEDIUM-CURRENT RANGE, CPSRM = 0, PIC16F1825/9 ONLY

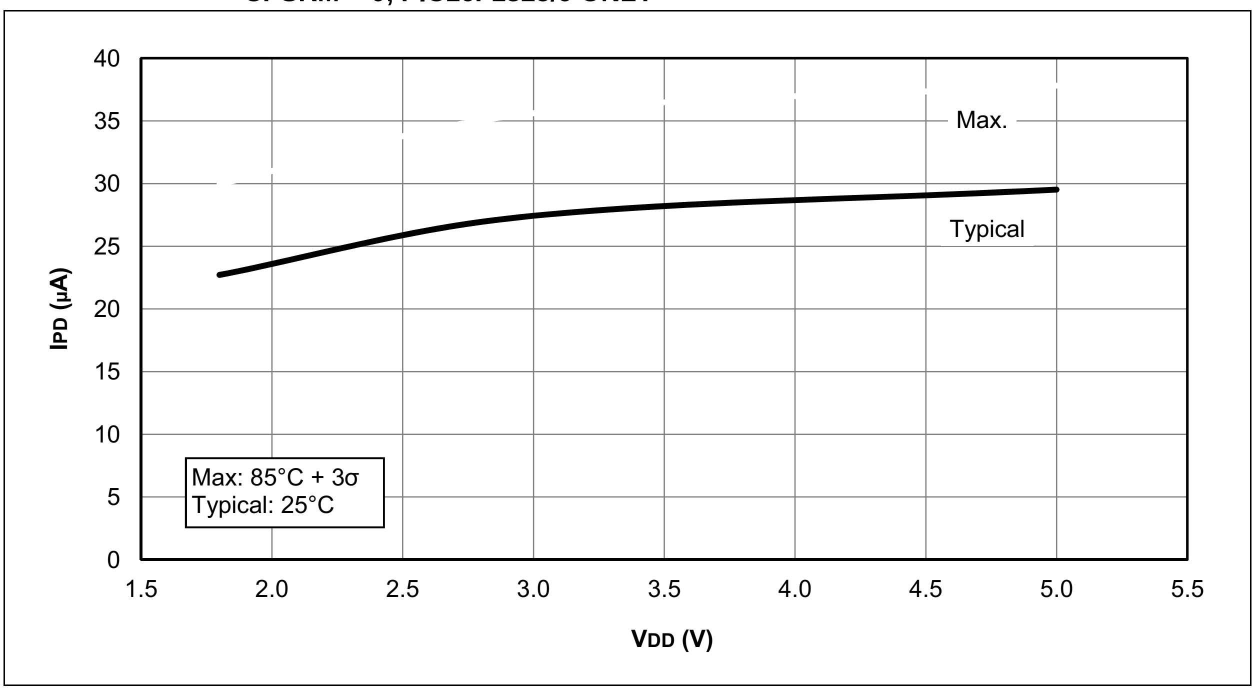


FIGURE 31-43: VOH vs. IOH OVER TEMPERATURE (VDD = 3.0V)

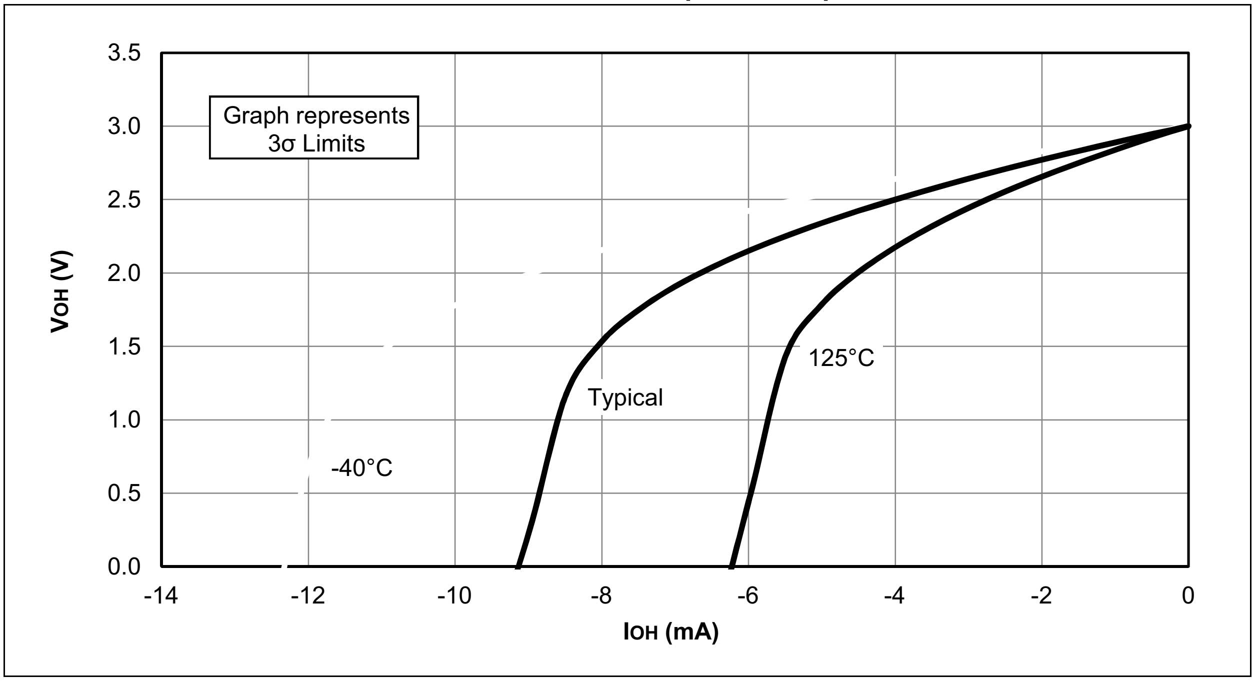
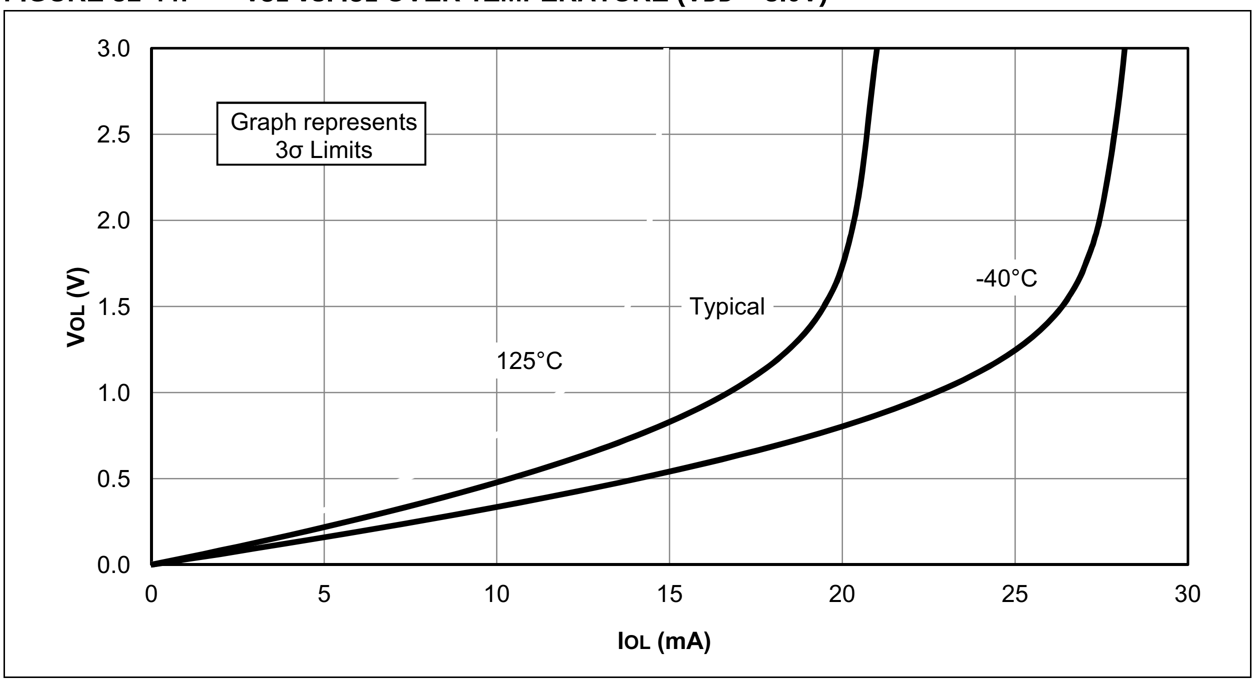
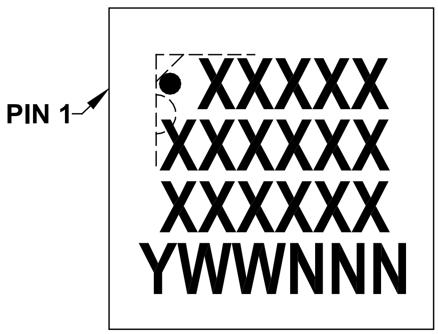


FIGURE 31-44: VOL vs. IOL OVER TEMPERATURE (VDD = 3.0V)

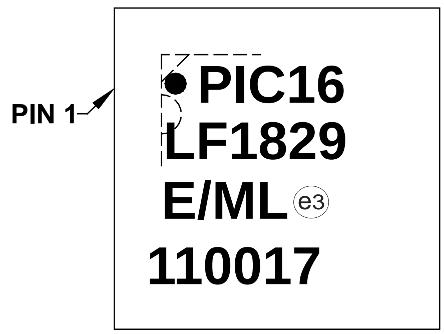


33.1 Package Marking Information (Continued)

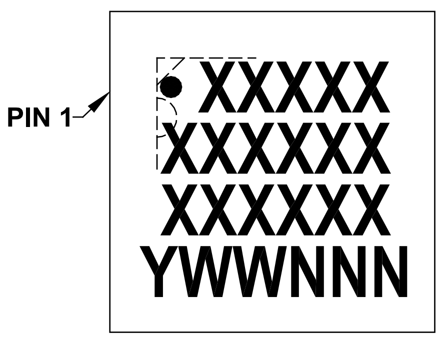
20-Lead QFN (4x4x0.9 mm)



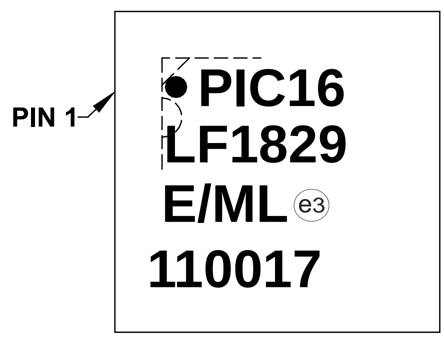
Example



20-Lead UQFN (4x4x0.5 mm)

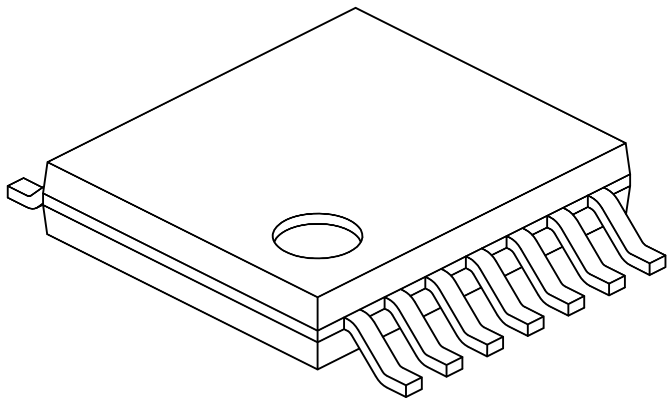


Example



14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	14		
Pitch	e	0.65 BSC		
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.80	1.00	1.05
Standoff	A1	0.05	-	0.15
Overall Width	E	6.40 BSC		
Molded Package Width	E1	4.30	4.40	4.50
Molded Package Length	D	4.90	5.00	5.10
Foot Length	L	0.45	0.60	0.75
Footprint	(L1)	1.00 REF		
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.19	-	0.30

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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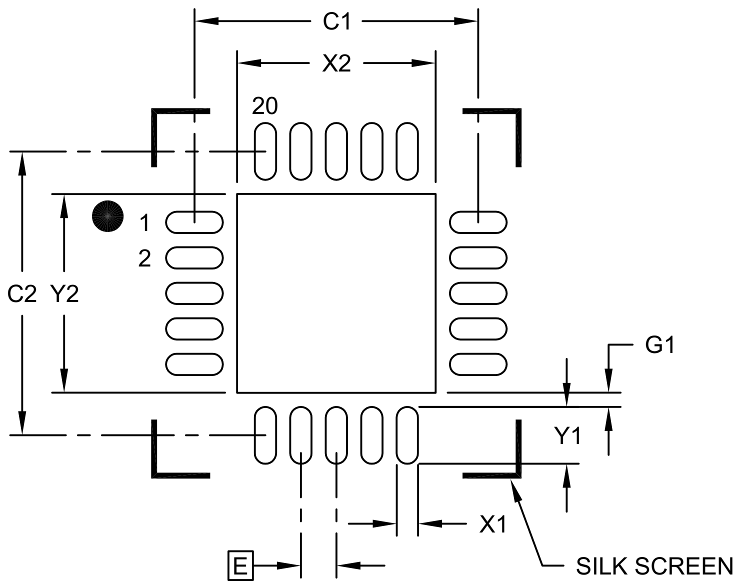
20-Lead Ultra Thin Plastic Quad Flat, No Lead Package (GZ) - 4x4x0.5 mm Body [UQFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	X2			2.80
Optional Center Pad Length	Y2			2.80
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X20)	X1			0.30
Contact Pad Length (X20)	Y1			0.80
Contact Pad to Center Pad (X20)	G1	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2255A

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (08/2010)

Original release.

Revision B (05/2011)

Revised Electrical Specifications.

Revision C (06/2012)

Updated the Family Types table; Updated Figures 1, 2 and 3; Updated Table 3-3; Changed all instances of SDO into SDO1, SDOSEL into SDO1SEL and SSSEL into SS1SEL; Added PIR3, PIR4, PIE3 and PIE4 to Table 3-3; Updated Register 4-2; Updated Sections 5.2.2.5 and 5.5.3; Added Note 1 to Table 11-3; Updated Figure 13-1 and Equation 16-1; Updated Section 19.9; Added charts to the DC and AC Characteristics Graphs section; Revised the Electrical Specifications section; Updated the Packaging Information section; Updated the Product Identification System section; Other minor corrections.

Revision D (05/2014)

Added new UQFN packages: 16-Lead, UQFN, 4x4x0.5, (JQ) and 20-Lead, UQFN, 4x4x0.5, (GZ) packages. Minor corrections.

Revision E (4/2015)

Added Section 30.9: High Temperature Operation in the Electrical Specifications section.

APPENDIX B: MIGRATING FROM OTHER PIC® DEVICES

This shows a comparison of features in the migration from the PIC16F648 device to the PIC16(L)F1825/9 family of devices.

This section provides comparisons when migrating from other similar PIC® devices to the PIC16(L)F1825/9 family of devices.

B.1 PIC16F648A to PIC16F1825/9

TABLE B-1: FEATURE COMPARISON

Feature	PIC16F648A	PIC16F1825/9
Max. Operating Speed	20 MHz	32 MHz
Max. Program Memory (Words)	4K	8K
Max. SRAM (Bytes)	256	1024
Max. EEPROM (Bytes)	256	256
A/D Resolution	10-bit	10-bit
Timers (8/16-bit)	2/1	4/1
Brown-out Reset	Y	Y
Internal Pull-ups	RB<7:0>	PIC16F1825: RA<5:0>, RC<5:0> PIC16F1829: RA<5:0>, RB<7:4>, RC<7:0>
Interrupt-on-change	RB<7:4>	PIC16F1825: RA<5:0>, Edge Selectable PIC16F1829: RA<5:0>, RB<7:4>, Edge Selectable
Comparator	2	2
AUSART/EUSART	1/0	0/1
Extended WDT	N	Y
Software Control Option of WDT/BOR	N	Y
INTOSC Frequencies	48 kHz or 4 MHz	31 kHz - 32 MHz
Clock Switching	Y	Y
Capacitive Sensing	N	Y
CCP/ECCP	2/0	2/2
Enhanced PIC16 CPU	N	Y
MSSPx/SSPx	0	2/0
Reference Clock	N	Y
Data Signal Modulator	N	Y
SR Latch	N	Y
Voltage Reference	N	Y
DAC	Y	Y